

1

2

3

4

MARK

DESCRIPTION

A

A

B

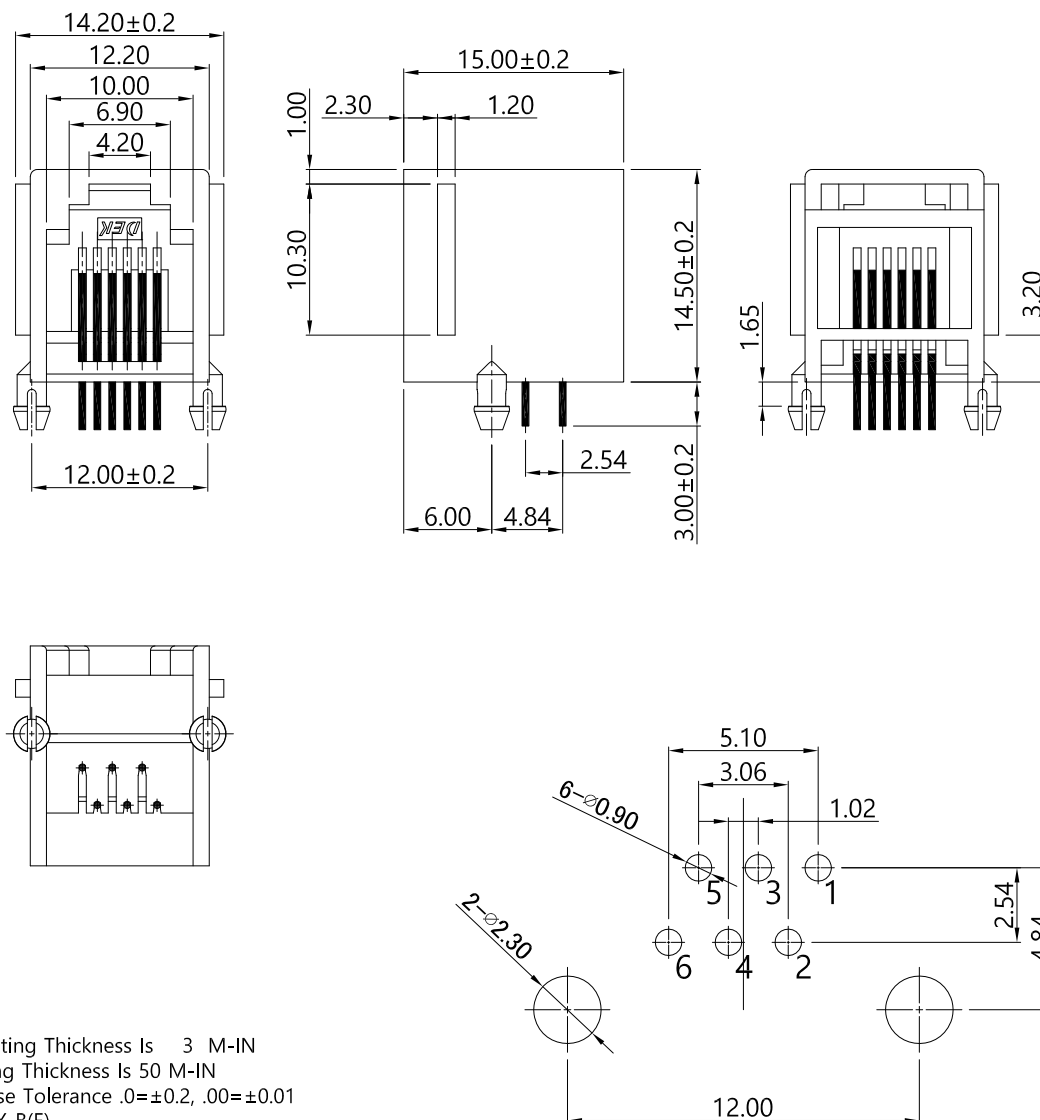
B

C

C

D

D



Note.

1. Gold Plating Thickness Is 3 M-IN
2. Ni Plating Thickness Is 50 M-IN
3. Otherwise Tolerance .0= $\pm 0.2$ , .00= $\pm 0.01$
4. 623PCBX-B(E)

Pin quantity : 2, 4, 6

Electrical

1. Voltage Rating : 125 VAC Rms
2. Current Rating: 1.5 AMP
3. Contact Resistance: 30 Milliohms Max
4. Insulation Resistance: 500 megohms min @500V DC
5. Dielectric Withstanding: Resistance: 1000V AC Rms 60Hz. 1Min
6. Durability: 750 Cycles Min
7. Operation Temperature:  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

PCB LAYOUT  
(Top View)

|      |             |               |                                  |                    |                    |                      |
|------|-------------|---------------|----------------------------------|--------------------|--------------------|----------------------|
| 2    |             | CONTACT PLATE | PHOSPHOR BRONZE                  | $\varnothing 0.46$ |                    |                      |
| 1    |             | HOUSING       | PBT                              |                    | Color : White Gray |                      |
| NO   | 部番 PART NO. | 名稱 TITLE      | 材料 MATERIAL                      | 規格 SPECIFICATION   | 處理 TREATMENT       | 備考 REMARK            |
|      |             |               | 三角法<br>THIRD ANGLE<br>PROJECTION | 單位 UNIT<br>mm      | 提出先<br>USER        | MODULAR JACK         |
|      |             |               | 承認<br>APPROVAL                   | 檢圖<br>CHECK        | 圖名<br>TITLE        | 623PCB6-B(E) (3M,WG) |
|      |             |               |                                  | 設計<br>DESIGN       | 圖番<br>Drawing No.  |                      |
| MARK | DATE        | APPR          | CHECK                            | DESIGN             |                    |                      |

DEK 대은전자주식회사

DEK개발 007모 A4(06. 11. 21)

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